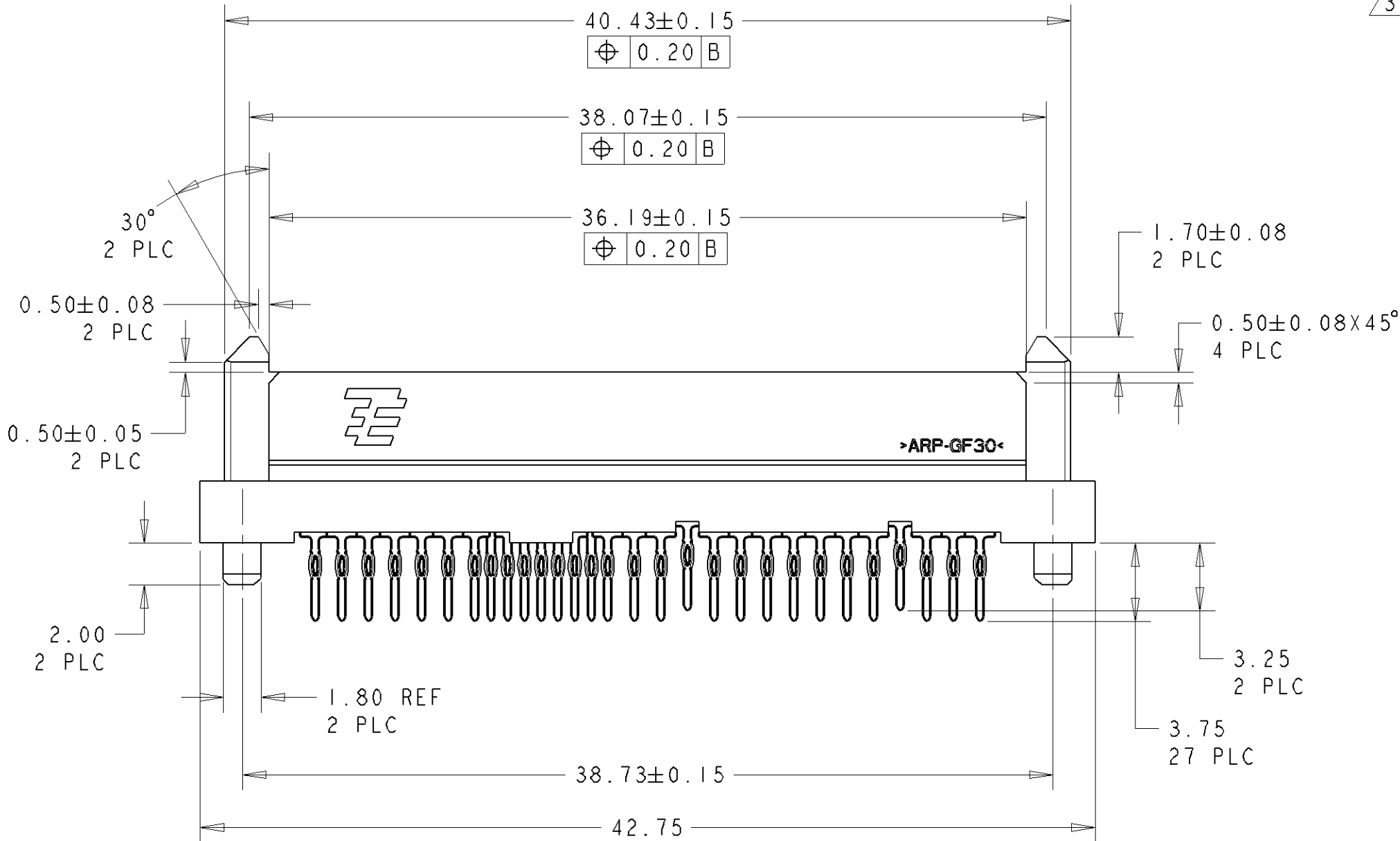
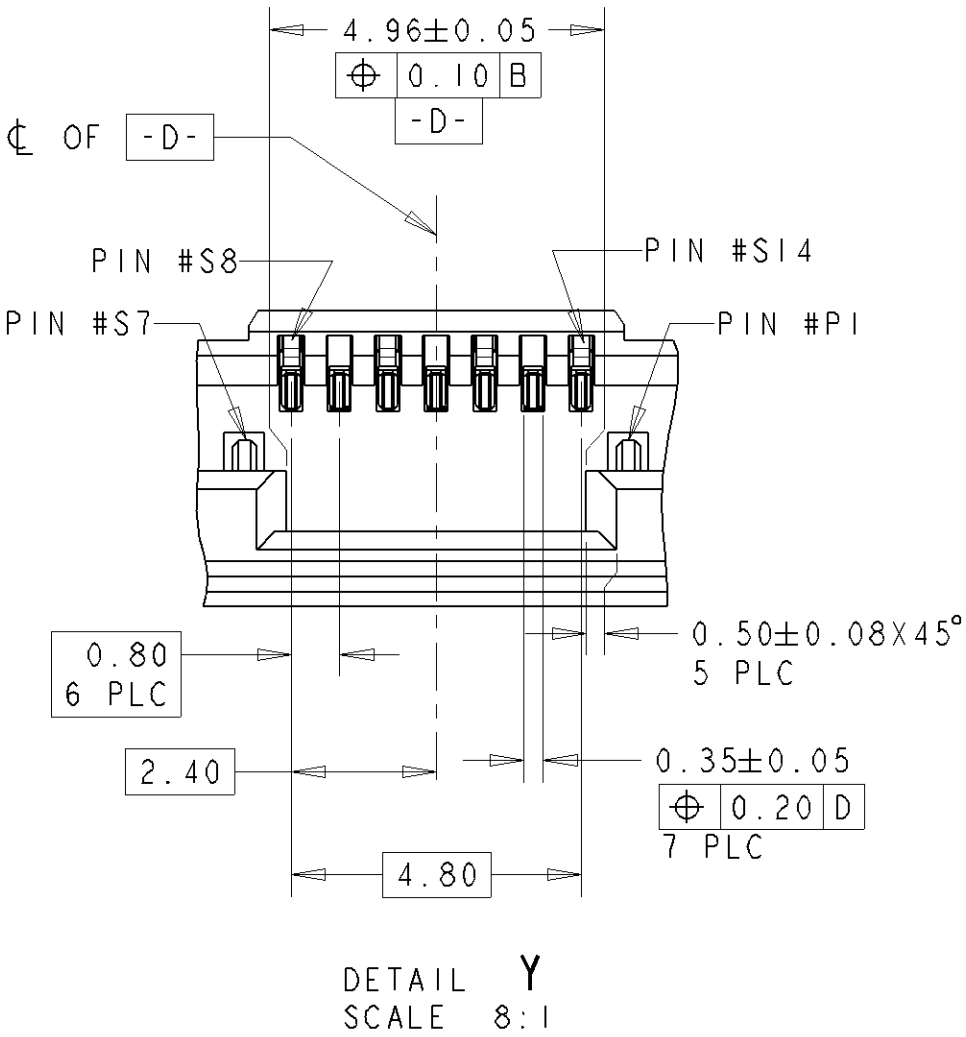
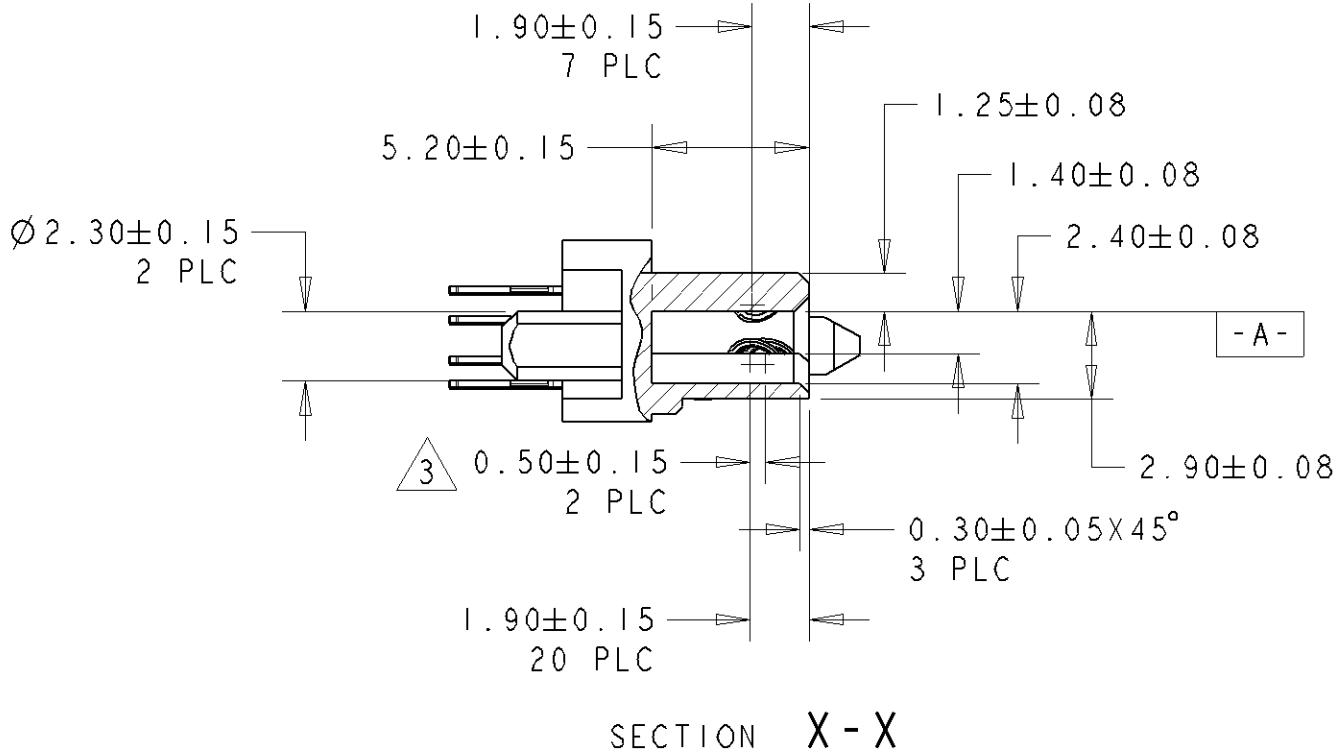
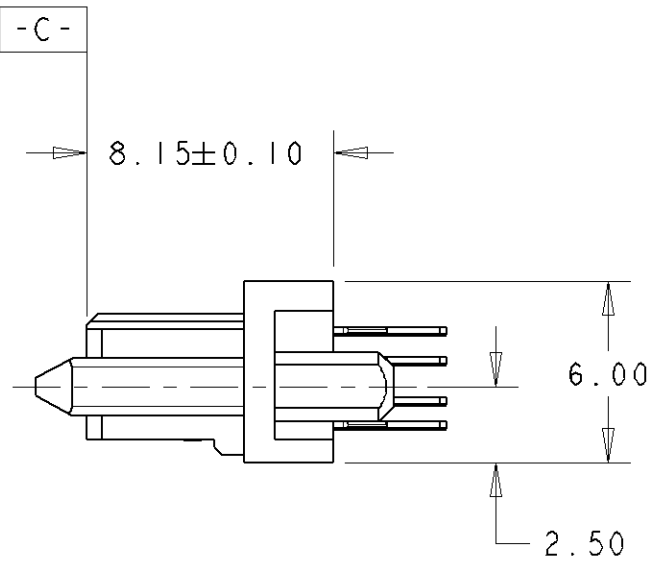
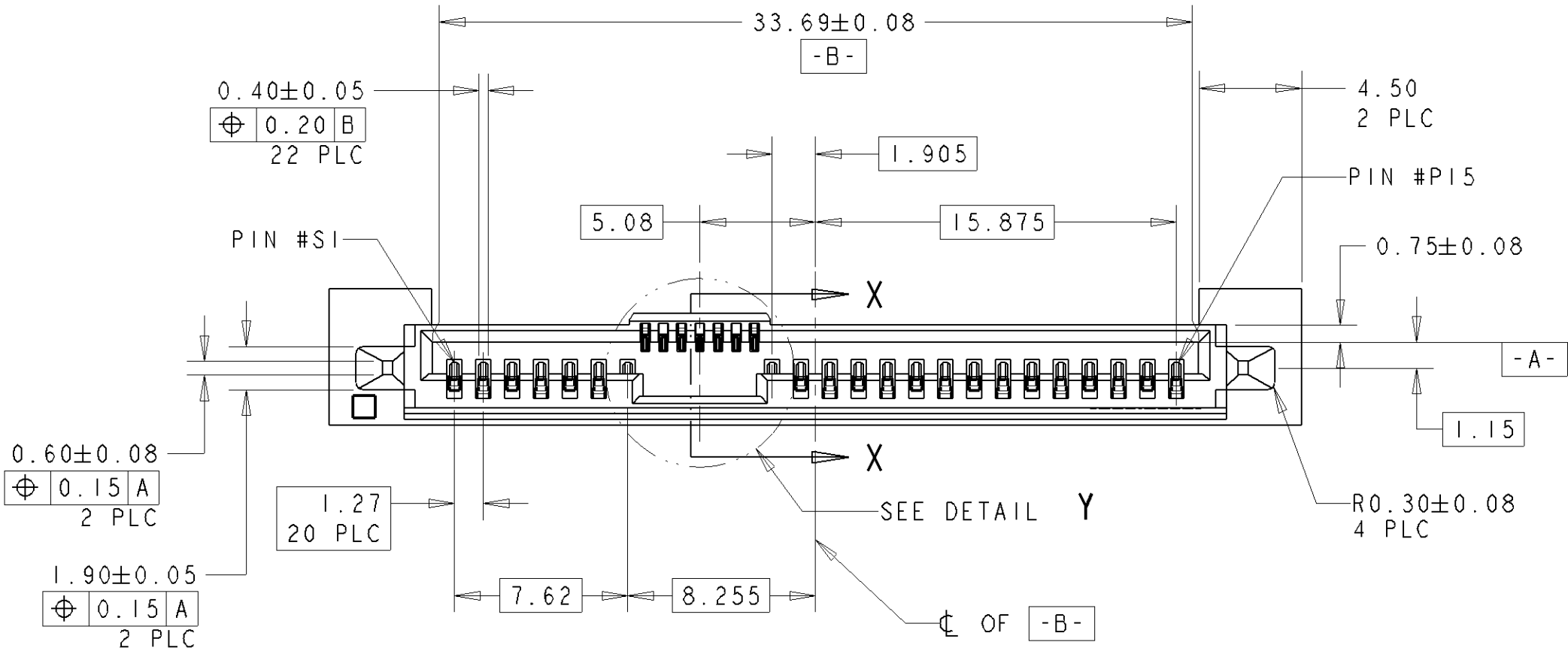


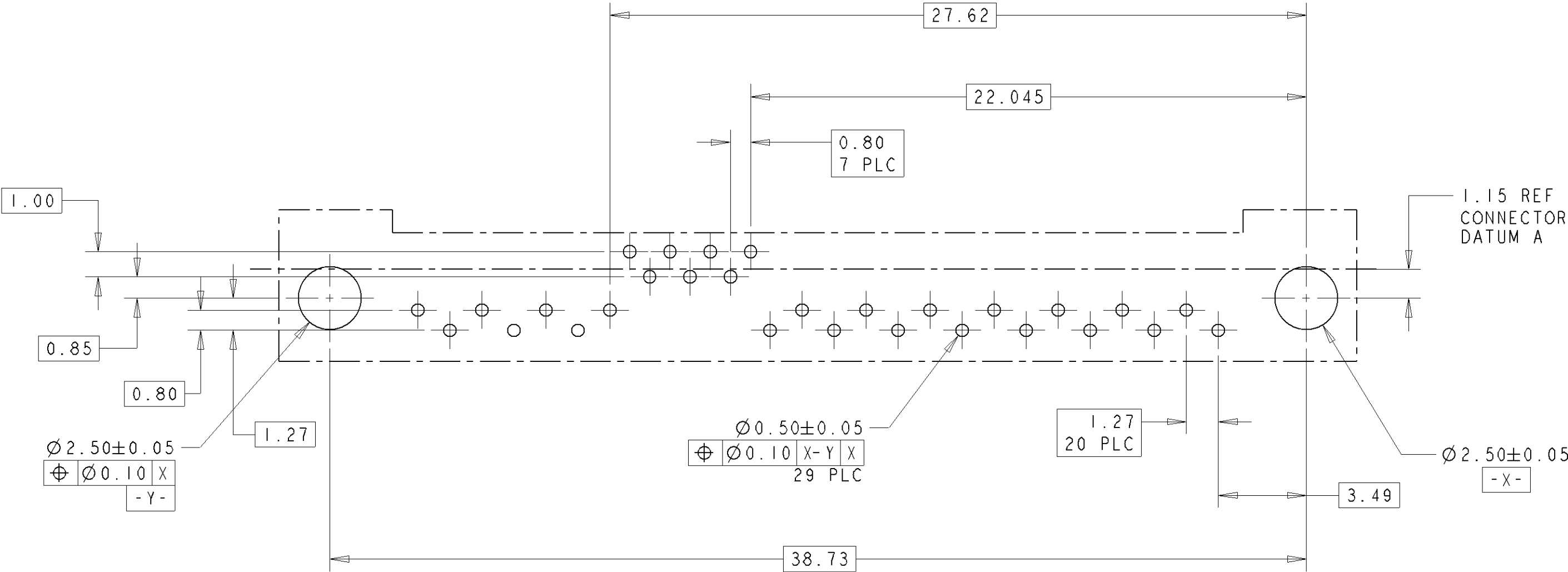
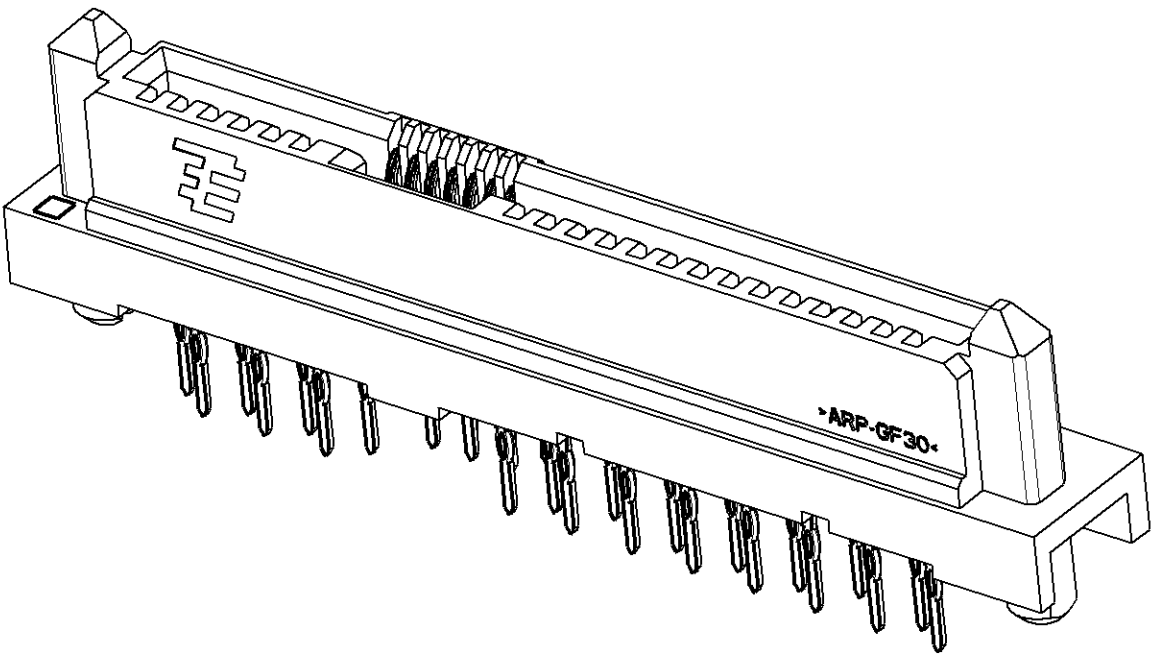
LOC	DIST	REVISIONS				
		P	LTR	DESCRIPTION	DATE	OWN APVD
DY	-	B		REVISED ECR-10-012418	11JUN10	PTY LSF

- NOTES:
- 1 MATERIAL:
HOUSING: HIGH TEMP THERMOPLASTIC, UL94V-0,
COLOR: BLACK
CONTACT: COPPER ALLOY
BOARDLOCK: COPPER ALLOY
- 2 FINISH:
CONTACT AREA: MIN 0.76um GOLD PLATING
SOLDERTAIL: MIN 2.54um MATTE TIN PLATING
UNDERPLATE: MIN 1.27um NICKEL PLATING
- 3 PIN #P4 AND #PI2 ONLY

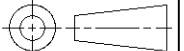


THIS DRAWING IS A CONTROLLED DOCUMENT FOR AMP INCORPORATED. IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.		OWN SK LEAW 31JUL2006	tyco Electronics Tyco Electronics Singapore Pte. Ltd.		
DIMENSIONS: mm		CHK SF LEONG 31JUL2006			
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD SF LEONG 31JUL2006	NAME SAS BACKPLANE RECEPTACLE, VERTICAL, PRESS-FIT		
0 PLC ± 1 PLC ± 2 PLC ±0.20 3 PLC ± 4 PLC ±		PRODUCT SPEC 108-51067			
ANGLES ±3° FINISH		APPLICATION SPEC 114-51013	SIZE CAGE CODE DRAWING NO A2 00779 C=1735368		
MATERIAL 1		WEIGHT -			
CUSTOMER DRAWING			SCALE 4:1 SHEET 1 OF 2 REV B		

LOC	DIST	REVISIONS				
		P	LTR	DESCRIPTION	DATE	DWN
DY	-	-	-	SEE SHEET 1	-	-



RECOMMENDED PCB LAYOUT
MIN BOARD THICKNESS: 1.44mm
SCALE 6:1

THIS DRAWING IS A CONTROLLED DOCUMENT FOR AMP INCORPORATED. IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.		DWN SK LEAW	31 JUL 2006	tyco <i>Electronics</i> Tyco Electronics Singapore Pte. Ltd.	
		CHK SF LEONG	31 JUL 2006		
DIMENSIONS: mm		APVD SF LEONG	31 JUL 2006	NAME SAS BACKPLANE RECEPTACLE, VERTICAL, PRESS-FIT	
		PRODUCT SPEC 108-51067			
	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.20 3 PLC ± 4 PLC ± ANGLES ±3° FINISH -	APPLICATION SPEC 114-51013		SIZE A2	CAGE CODE 00779
		MATERIAL -		WEIGHT -	DRAWING NO C=1735368
CUSTOMER DRAWING				SCALE 4:1	SHEET 2 OF 2